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10/ April
(N.E.)
F.22.03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding
Frames

RESPONSE TO FEBRUARY 11, 2003 OFFICE ACTION

To: Box Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

From: D. Brent Kenady
Tel. 509-624-4276; Fax 509-838-3424
Wells St. John P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3828

Responsive to the Office Action dated February 11, 2003, Applicant
amends and remarks as follows:

AMENDMENTS**RECEIVED**

APR 21 2003

TECHNOLOGY CENTER R3700